

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	EMBEDDED PROCESSING/26/16067	
1.3 Title of PCN	ST Shenzhen (China) assembly site and HHgrace (China) Diffusion site additional source for STM32H74x and STM32H75x listed products in LQFP 20x20 and LQFP 24x24 packages.	
1.4 Product Category	STM32H742x, STM32H743x, STM32H750x and STM32H753x	
1.5 Issue date	2026-04-21	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Patrick AIDOUNE
2.1.2 Marketing Manager	Marie TOURNUT
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	ST Shenzhen (China), HHGrace (China)

4. Description of change

	Old	New
4.1 Description	<p>Current assembly sites (depending on package size) with Crolles Diffusion source:</p> <ul style="list-style-type: none"> - AMKOR ATP (Philippine) Gold wire, - AMKOR ATP (Philippine) Copper Palladium wire, - ASE Kaohsiung (Taiwan) Gold wire, - ASE Kaohsiung (Taiwan) Copper Palladium wire , <p>You may refer to 16067_Additional information.pdf document for further details.</p>	<p>Current assembly sites (depending on package size) with Crolles Diffusion source:</p> <ul style="list-style-type: none"> - AMKOR ATP (Philippine) Gold wire, - AMKOR ATP (Philippine) Copper Palladium wire, - ASE Kaohsiung (Taiwan) Gold wire, - ASE Kaohsiung (Taiwan) Copper Palladium wire , <p>Additional assembly site with HHGrace Diffusion Source for extended capacity:</p> <ul style="list-style-type: none"> - ST Shenzhen (China) Copper Alloy wire .
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact on Form, Fit or Function	

5. Reason / motivation for change

5.1 Motivation	Due to the success on the market of STM32 devices, ST General Purpose and Automotive Microcontrollers division decided to qualify an additional back-end site to maintain state of the art service level to our customers thanks to extra capacity.
5.2 Customer Benefit	SERVICE IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	<p>Change is visible on the marking</p> <ul style="list-style-type: none"> - Back-End Assembly Site code: <ul style="list-style-type: none"> • GK : ST Shenzhen (China) New Assembly site • 7B : AMKOR ATP (Philippines) • AA : ASE KaoHsiung (Taiwan) - Diffusion plant code WX: <ul style="list-style-type: none"> • VQ : ST Crolles 300 (France) • Y5 : HHGrace WuXi (China) Fab 7 New Diffusion site • 2E : HHGrace WuXi (China) Fab 9 New Diffusion site <p>Please refer to PCN 16067_Additional information.pdf document for further details.</p>
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7. Timing / schedule	
7.1 Date of qualification results	2026-06-15
7.2 Intended start of delivery	2026-06-22
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation			
8.1 Description	16067 MDRF-GPAM-RER2506 PCN16067 - ST Shenzhen LQFP 20x20 and LQFP 24x24 packages - reliability plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2026-04-21

9. Attachments (additional documentations)	
16067 Public product.pdf	
16067 MDRF-GPAM-RER2506 PCN16067 - ST Shenzhen LQFP 20x20 and LQFP 24x24 packages - reliability plan.pdf	
16067 _Additional information.pdf	

10. Affected parts		
10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32H742ZGT6	
	STM32H743IGT6	
	STM32H743IIT6	
	STM32H743ZGT6	
	STM32H743ZIT6	
	STM32H743ZIT6TR	
	STM32H750IBT6	
	STM32H750ZBT6	
	STM32H753IIT6	
	STM32H753ZIT6	

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